

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS:**

Claims 1-8 (Canceled)

-- 9. (New) A semiconductor device test probe having a tip portion for being urged against a plurality of electrode pads of an integrated semiconductor device to establish electrical contacts between the tip portion and the electrode pads for testing an operation of the semiconductor;

said test probe having a side surface portion and a tip portion, said tip portion defining a spherical surface and said spherical surface having a radius of curvature  $r$  expressed by  $10\ \mu\text{m} \leq r \leq 20\ \mu\text{m}$ . --